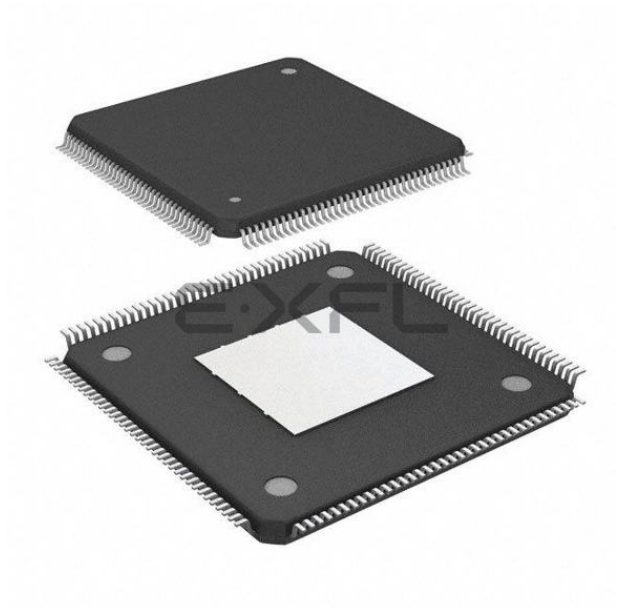

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

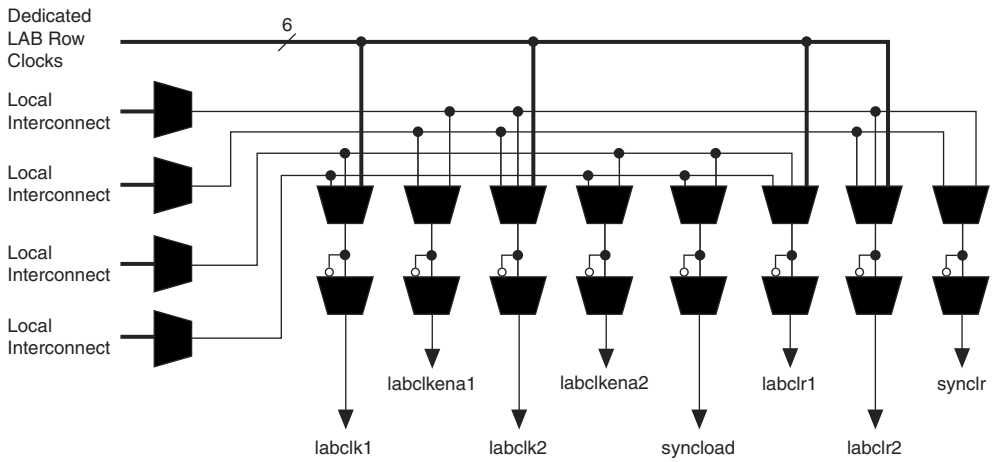
Details	
Product Status	Active
Number of LABs/CLBs	392
Number of Logic Elements/Cells	6272
Total RAM Bits	276480
Number of I/O	91
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	144-LQFP Exposed Pad
Supplier Device Package	144-EQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce6e22i7n

Each LAB can use two clocks and two clock enable signals. The clock and clock enable signals of each LAB are linked. For example, any LE in a particular LAB using the `labclk1` signal also uses the `labclkena1`. If the LAB uses both the rising and falling edges of a clock, it also uses both LAB-wide clock signals. Deasserting the clock enable signal turns off the LAB-wide clock.

The LAB row clocks `[5..0]` and LAB local interconnect generate the LAB-wide control signals. The MultiTrack interconnect inherent low skew allows clock and control signal distribution in addition to data distribution.

Figure 2–6 shows the LAB control signal generation circuit.

Figure 2–6. Cyclone IV Device LAB-Wide Control Signals



LAB-wide signals control the logic for the clear signal of the register. The LE directly supports an asynchronous clear function. Each LAB supports up to two asynchronous clear signals (`labclr1` and `labclr2`).

A LAB-wide asynchronous load signal to control the logic for the preset signal of the register is not available. The register preset is achieved with a NOT gate push-back technique. Cyclone IV devices only support either a preset or asynchronous clear signal.

In addition to the clear port, Cyclone IV devices provide a chip-wide reset pin (`DEV_CLRn`) that resets all registers in the device. An option set before compilation in the Quartus II software controls this pin. This chip-wide reset overrides all other control signals.

Document Revision History

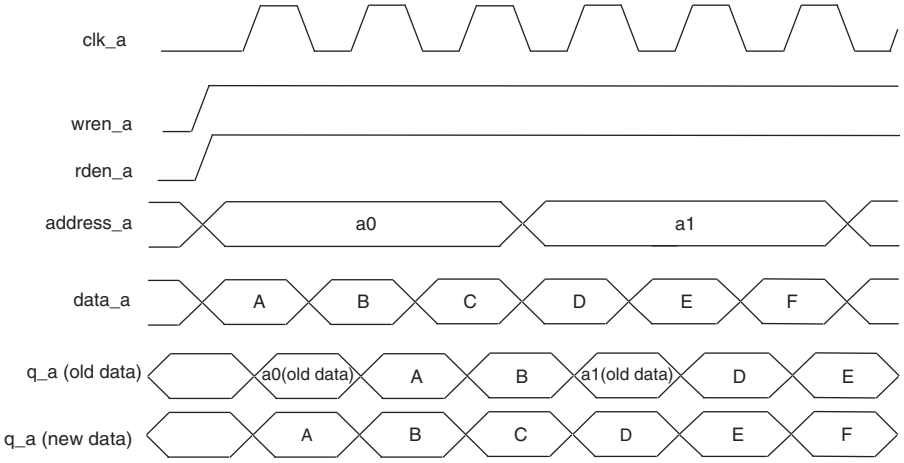
Table 2–1 shows the revision history for this chapter.

Table 2–1. Document Revision History

Date	Version	Changes
November 2009	1.0	Initial release.

Figure 3–7 shows a timing waveform for read and write operations in single-port mode with unregistered outputs. Registering the outputs of the RAM simply delays the q output by one clock cycle.

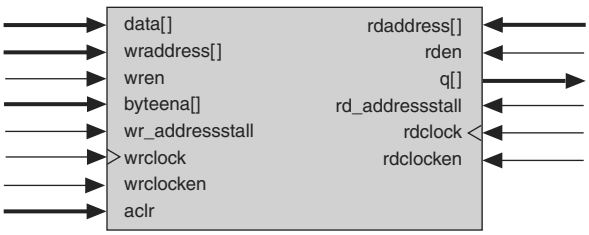
Figure 3–7. Cyclone IV Devices Single-Port Mode Timing Waveform



Simple Dual-Port Mode

Simple dual-port mode supports simultaneous read and write operations to different locations. Figure 3–8 shows the simple dual-port memory configuration.

Figure 3–8. Cyclone IV Devices Simple Dual-Port Memory *(1)*



Note to Figure 3–8:

(1) Simple dual-port RAM supports input or output clock mode in addition to the read or write clock mode shown.

Cyclone IV devices M9K memory blocks support mixed-width configurations, allowing different read and write port widths. Table 3–3 lists mixed-width configurations.

Table 3–3. Cyclone IV Devices M9K Block Mixed-Width Configurations (Simple Dual-Port Mode) ***(Part 1 of 2)***

Read Port	Write Port								
	8192 × 1	4096 × 2	2048 × 4	1024 × 8	512 × 16	256 × 32	1024 × 9	512 × 18	256 × 36
8192 × 1	✓	✓	✓	✓	✓	✓	—	—	—
4096 × 2	✓	✓	✓	✓	✓	✓	—	—	—
2048 × 4	✓	✓	✓	✓	✓	✓	—	—	—
1024 × 8	✓	✓	✓	✓	✓	✓	—	—	—

Table 4–2 lists the sign of the multiplication results for the various operand sign representations. The results of the multiplication are signed if any one of the operands is a signed value.

Table 4–2. Multiplier Sign Representation

Data A		Data B		Result
signa Value	Logic Level	signb Value	Logic Level	
Unsigned	Low	Unsigned	Low	Unsigned
Unsigned	Low	Signed	High	Signed
Signed	High	Unsigned	Low	Signed
Signed	High	Signed	High	Signed

Each embedded multiplier block has only one `signa` and one `signb` signal to control the sign representation of the input data to the block. If the embedded multiplier block has two 9 × 9 multipliers, the `Data A` input of both multipliers share the same `signa` signal, and the `Data B` input of both multipliers share the same `signb` signal. You can dynamically change the `signa` and `signb` signals to modify the sign representation of the input operands at run time. You can send the `signa` and `signb` signals through a dedicated input register. The multiplier offers full precision, regardless of the sign representation.

☞ When the `signa` and `signb` signals are unused, the Quartus II software sets the multiplier to perform unsigned multiplication by default.

Output Registers

You can register the embedded multiplier output with output registers in either 18- or 36-bit sections, depending on the operational mode of the multiplier. The following control signals are available for each output register in the embedded multiplier:

- clock
- clock enable
- asynchronous clear

All input and output registers in a single embedded multiplier are fed by the same clock, clock enable, and asynchronous clear signals.

Operational Modes

You can use an embedded multiplier block in one of two operational modes, depending on the application needs:

- One 18 × 18 multiplier
- Up to two 9 × 9 independent multipliers

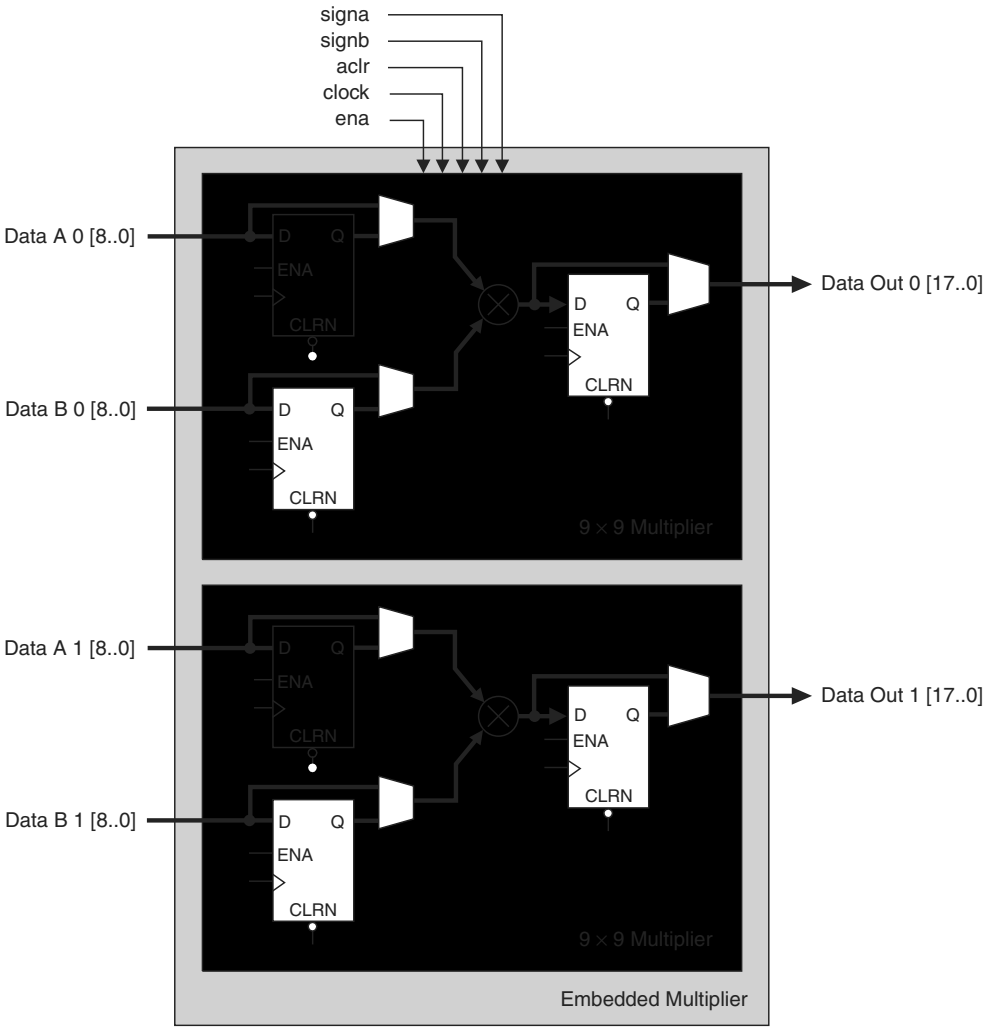
☞ You can also use embedded multipliers of Cyclone IV devices to implement multiplier adder and multiplier accumulator functions, in which the multiplier portion of the function is implemented with embedded multipliers, and the adder or accumulator function is implemented in logic elements (LEs).

9-Bit Multipliers

You can configure each embedded multiplier to support two 9 × 9 independent multipliers for input widths of up to 9 bits.

Figure 4–4 shows the embedded multiplier configured to support two 9-bit multipliers.

Figure 4–4. 9-Bit Multiplier Mode



All 9-bit multiplier inputs and results are independently sent through registers. The multiplier inputs can accept signed integers, unsigned integers, or a combination of both. Two 9 × 9 multipliers in the same embedded multiplier block share the same `signa` and `signb` signal. Therefore, all the `Data A` inputs feeding the same embedded multiplier must have the same sign representation. Similarly, all the `Data B` inputs feeding the same embedded multiplier must have the same sign representation.

Table 6–2 lists the I/O standards that support impedance matching and series termination.

Table 6–2. Cyclone IV Device I/O Features Support (Part 1 of 2)

I/O Standard	IOH/IOL Current Strength Setting (mA) (1), (9)		R_S OCT with Calibration Setting, Ohm (Ω)		R_S OCT Without Calibration Setting, Ohm (Ω)		Cyclone IV E I/O Banks Support	Cyclone IV GX I/O Banks Support	Slew Rate Option (6)	PCI-clamp Diode Support
	Column I/O	Row I/O	Column I/O	Row I/O (8)	Column I/O	Row I/O (8)				
3.3-V LVTTL	4,8	4,8	—	—	—	—	1,2,3,4,5,6,7,8	3,4,5,6,7,8,9	—	✓
3.3-V LVCMOS	2	2	—	—	—	—			—	✓
3.0-V LVTTL	4,8,12,16	4,8,12,16	50,25	50,25	50,25	50,25			0,1,**2**	✓
3.0-V LVCMOS	4,8,12,16	4,8,12,16	50,25	50,25	50,25	50,25				✓
3.0-V PCI/PCI-X	—	—	—	—	—	—			—	✓
2.5-V LVTTL/LVCMOS	4,8,12,16	4,8,12,16	50,25	50,25	50,25	50,25			0,1,**2**	✓
1.8-V LVTTL/LVCMOS	2,4,6,8,10,12,16	2,4,6,8,10,12,16	50,25	50,25	50,25	50,25				—
1.5-V LVCMOS	2,4,6,8,10,12,16	2,4,6,8,10,12,16	50,25	50,25	50,25	50,25				—
1.2-V LVCMOS	2,4,6,8,10,12	2,4,6,8,10	50,25	50	50,25	50		4,5,6,7,8		—
SSTL-2 Class I	8,12	8,12	50	50	50	50		3,4,5,6,7,8,9		—
SSTL-2 Class II	16	16	25	25	25	25				—
SSTL-18 Class I	8,10,12	8,10,12	50	50	50	50				—
SSTL-18 Class II	12,16	12,16	25	25	25	25				—
HSTL-18 Class I	8,10,12	8,10,12	50	50	50	50				—
HSTL-18 Class II	16	16	25	25	25	25				—
HSTL-15 Class I	8,10,12	8,10,12	50	50	50	50				—
HSTL-15 Class II	16	16	25	25	25	25				—
HSTL-12 Class I	8,10,12	8,10	50	50	50	50		4,5,6,7,8		—
HSTL-12 Class II	14	—	25	—	25	—	3,4,7,8	4,7,8		—
Differential SSTL-2 Class I (2), (7)	8,12	8,12	50	50	50	50	1,2,3,4,5,6,7,8	3,4,5,6,7,8	0,1,**2**	—
Differential SSTL-2 Class II (2), (7)	16	16	25	25	25	25				—
Differential SSTL-18 (2), (7)	8,10,12	—	50	—	50	—				—
Differential HSTL-18 (2), (7)	8,10,12	—	50	—	50	—				—
Differential HSTL-15 (2), (7)	8,10,12	—	50	—	50	—				—
Differential HSTL-12 (2), (7)	8,10,12	—	50	—	50	—	3,4,7,8	4,7,8		—

Figure 6–16. RSDS, Mini-LVDS, or PPDS Interface with External Resistor Network on the Top and Bottom I/O Banks *(1)*

Note to Figure 6–16:

(1) R_S and R_P values are pending characterization.

A resistor network is required to attenuate the output voltage swing to meet RSDS, mini-LVDS, and PPDS specifications when using emulated transmitters. You can modify the resistor network values to reduce power or improve the noise margin.

The resistor values chosen must satisfy Equation 6–1.

Equation 6–1. Resistor Network

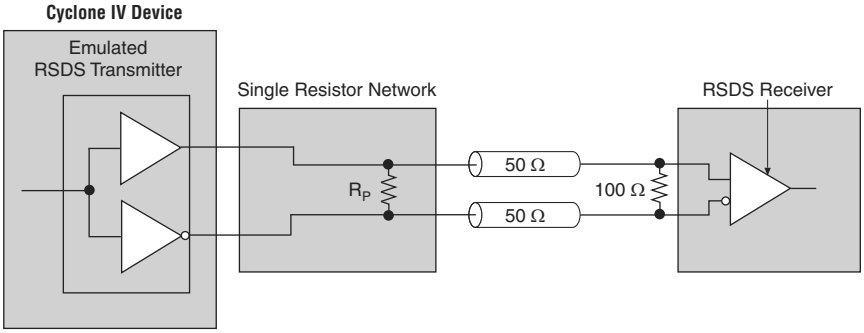
$$\frac{R_S \times \frac{R_P}{2}}{R_S + \frac{R_P}{2}} = 50\ \Omega$$

Altera recommends that you perform simulations using Cyclone IV devices IBIS models to validate that custom resistor values meet the RSDS, mini-LVDS, or PPDS requirements.

It is possible to use a single external resistor instead of using three resistors in the resistor network for an RSDS interface, as shown in Figure 6–17. The external single-resistor solution reduces the external resistor count while still achieving the required signaling level for RSDS. However, the performance of the single-resistor solution is lower than the performance with the three-resistor network.

Figure 6–17 shows the RSDS interface with a single resistor network on the top and bottom I/O banks.

Figure 6–17. RSDS Interface with Single Resistor Network on the Top and Bottom I/O Banks *(1)*



Note to Figure 6–17:

(1) R_P value is pending characterization.

implements either a high-speed deserializer receiver or a high-speed serializer transmitter. There is a list of parameters in the ALTLVDS megafunction that you can set to customize your SERDES based on your design requirements. The megafunction is optimized to use Cyclone IV devices resources to create high-speed I/O interfaces in the most effective manner.

When you use Cyclone IV devices with the ALTLVDS megafunction, the interface always sends the MSB of your parallel data first.

For more details about designing your high-speed I/O systems interfaces using the ALTLVDS megafunction, refer to the *ALTLVDS Megafunction User Guide* and the *Quartus II Handbook*.

Document Revision History

Table 6–12 lists the revision history for this chapter.

Table 6–12. Document Revision History (Part 1 of 2)

Date	Version	Changes
March 2016	2.7	■ Updated Table 6–5 and Table 6–9 to remove support for the N148 package.
May 2013	2.6	■ Updated Table 6–2 by adding Note (9). ■ Updated Table 6–4 and Table 6–8 to add new device options and packages.
February 2013	2.5	Updated Table 6–4 and Table 6–8 to add new device options and packages.
October 2012	2.4	■ Updated "I/O Banks" and "High Speed Serial Interface (HSSI) Input Reference Clock Support " sections. ■ Updated Table 6–3 and Table 6–5. ■ Updated Figure 6–10.
November 2011	2.3	■ Updated "Differential SSTL I/O Standard Support in Cyclone IV Devices" and "Differential HSTL I/O Standard Support in Cyclone IV Devices" sections. ■ Updated Table 6–1, Table 6–8, and Table 6–9. ■ Updated Figure 6–1.
December 2010	2.2	■ Updated for the Quartus II software version 10.1 release. ■ Added Cyclone IV E new device package information. ■ Added "Clock Pins Functionality" section. ■ Updated Table 6–4 and Table 6–8. ■ Minor text edits.
July 2010	2.1	■ Updated "Cyclone IV I/O Elements", "Programmable Pull-Up Resistor", "I/O Banks", "High-Speed I/O Interface", and "Designing with BLVDS" sections. ■ Updated Table 6–6 and Table 6–7. ■ Updated Figure 6–19.

Configuration Process

This section describes Cyclone IV device configuration requirements and includes the following topics:

For more information about the Altera® FPGA configuration cycle state machine, refer to the *Configuring Altera FPGAs* chapter in volume 1 of the *Configuration Handbook*.

Power Up

If the device is powered up from the power-down state, V_{CCINT}, V_{CCA}, and V_{CCIO} (for the I/O banks in which the configuration and JTAG pins reside) must be powered up to the appropriate level for the device to exit from POR.

Reset

After power up, Cyclone IV devices go through POR. POR delay depends on the MSEL pin settings, which correspond to your configuration scheme. During POR, the device resets, holds nSTATUS and CONF_DONE low, and tri-states all user I/O pins (for PS and FPP configuration schemes only).

To tri-state the configuration bus for AS and AP configuration schemes, you must tie nCE high and nCONFIG low.

The user I/O pins and dual-purpose I/O pins have weak pull-up resistors, which are always enabled (after POR) before and during configuration. When the device exits POR, all user I/O pins continue to tri-state. While nCONFIG is low, the device is in reset. When nCONFIG goes high, the device exits reset and releases the open-drain nSTATUS pin, which is then pulled high by an external 10-kΩ pull-up resistor. After nSTATUS is released, the device is ready to receive configuration data and the configuration stage starts.

For more information about the value of the weak pull-up resistors on the I/O pins that are on before and during configuration, refer to the *Cyclone IV Device Datasheet* chapter.

Configuration

Configuration data is latched into the Cyclone IV device at each DCLK cycle. However, the width of the data bus and the configuration time taken for each scheme are different. After the device receives all the configuration data, the device releases the open-drain CONF_DONE pin, which is pulled high by an external 10-kΩ pull-up resistor. A low-to-high transition on the CONF_DONE pin indicates that the configuration is complete and initialization of the device can begin.

Table 8–13. FPP Timing Parameters for Cyclone IV Devices (Part 2 of 2)

Symbol	Parameter	Minimum		Maximum		Unit
		Cyclone IV (1)	Cyclone IV E (2)	Cyclone IV (1)	Cyclone IV E (2)	
t_{ST2CK}	nSTATUS high to first rising edge of DCLK	2		—		µs
t_{DH}	Data hold time after rising edge on DCLK	0		—		ns
t_{CD2UM}	CONF_DONE high to user mode (5)	300		650		µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period		—		—
t_{CD2UMC}	CONF_DONE high to user mode with **CLKUSR** option on	t_{CD2CU} + (3,192 × CLKUSR period)		—		—
t_{DSU}	Data setup time before rising edge on DCLK	5	8	—	—	ns
t_{CH}	DCLK high time	3.2	6.4	—	—	ns
t_{CL}	DCLK low time	3.2	6.4	—	—	ns
t_{CLK}	DCLK period	7.5	15	—	—	ns
f_{MAX}	DCLK frequency (6)	—	—	133	66	MHz

Notes to Table 8–13:

(1) Applicable for Cyclone IV GX and Cyclone IV E with 1.2-V core voltage.
(2) Applicable for Cyclone IV E with 1.0-V core voltage.
(3) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
(4) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
(5) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for starting the device.
(6) Cyclone IV E devices with 1.0-V core voltage have slower F_{MAX} when compared with Cyclone IV GX devices with 1.2-V core voltage.

JTAG Configuration

JTAG has developed a specification for boundary-scan testing (BST). The BST architecture offers the capability to efficiently test components on PCBs with tight lead spacing. The BST architecture can test pin connections without using physical test probes and capture functional data while a device is normally operating. You can also use the JTAG circuitry to shift configuration data into the device. The Quartus II software automatically generates **.sof** for JTAG configuration with a download cable in the Quartus II software Programmer.

For more information about the JTAG boundary-scan testing, refer to the *JTAG Boundary-Scan Testing for Cyclone IV Devices* chapter.

Programming Serial Configuration Devices In-System with the JTAG Interface

Cyclone IV devices in a single- or multiple-device chain support in-system programming of a serial configuration device with the JTAG interface through the SFL design. The intelligent host or download cable of the board can use the four JTAG pins on the Cyclone IV device to program the serial configuration device in system, even if the host or download cable cannot access the configuration pins (DCLK, DATA, ASDI, and nCS pins).

The SFL design is a JTAG-based in-system programming solution for Altera serial configuration devices. The SFL is a bridge design for the Cyclone IV device that uses their JTAG interface to access the EPCS JTAG Indirect Configuration Device Programming (**.jic**) file and then uses the AS interface to program the EPCS device. Both the JTAG interface and AS interface are bridged together inside the SFL design.

In a multiple device chain, you must only configure the master device that controls the serial configuration device. Slave devices in the multiple device chain that are configured by the serial configuration device do not have to be configured when using this feature. To successfully use this feature, set the MSEL pins of the master device to select the AS configuration scheme (Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9). The serial configuration device in-system programming through the Cyclone IV device JTAG interface has three stages, which are described in the following sections:

- "Loading the SFL Design"
- "ISP of the Configuration Device" on page 8–56
- "Reconfiguration" on page 8–57

Loading the SFL Design

The SFL design is a design inside the Cyclone IV device that bridges the JTAG interface and AS interface with glue logic.

The intelligent host uses the JTAG interface to configure the master device with a SFL design. The SFL design allows the master device to control the access of four serial configuration device pins, also known as the Active Serial Memory Interface (ASMI) pins, through the JTAG interface. The ASMI pins are serial clock input (DCLK), serial data output (DATA), AS data input (ASDI), and active-low chip select (nCS) pins.

Use the ACTIVE_DISENGAGE instruction with the CONFIG_IO instruction to interrupt configuration. Table 8–16 lists the sequence of instructions to use for various CONFIG_IO usage scenarios.

Table 8–16. JTAG CONFIG_IO (without JTAG_PROGRAM) Instruction Flows *(1)*

JTAG Instruction	Configuration Scheme and Current State of the Cyclone IV Device											
	Prior to User Mode (Interrupting Configuration)				User Mode				Power Up			
	PS	FPP	AS	AP	PS	FPP	AS	AP	PS	FPP	AS	AP
ACTIVE_DISENGAGE	O	O	O	O	O	O	O	O	—	—	—	—
CONFIG_IO	R	R	R	R	R	R	R	R	NA	NA	NA	NA
JTAG Boundary Scan Instructions (no JTAG_PROGRAM)	O	O	O	O	O	O	O	O	—	—	—	—
ACTIVE_ENGAGE	A	A	R *(2)*	R *(2)*	A	A	R *(2)*	R *(2)*	—	—	—	—
PULSE_NCONFIG			A *(3)*	A *(3)*			O	O	—	—	—	—
Pulse nCONFIG pin			A *(3)*	A *(3)*			O	O	—	—	—	—
JTAG TAP Reset	R	R	R	R	R	R	R	R	—	—	—	—

Notes to Table 8–16:

(1) You must execute "R" indicates that the instruction before the next instruction, "O" indicates the optional instruction, "A" indicates that the instruction must be executed, and "NA" indicates that the instruction is not allowed in this mode.

(2) Required if you use ACTIVE_DISENGAGE.

(3) Neither of the instruction is required if you use ACTIVE_ENGAGE.

The CONFIG_IO instruction does not hold nSTATUS low until reconfiguration. You must disengage the AS or AP configuration controller by issuing the ACTIVE_DISENGAGE and ACTIVE_ENGAGE instructions when active configuration is interrupted. You must issue the ACTIVE_DISENGAGE instruction alone or prior to the CONFIG_IO instruction if the JTAG_PROGRAM instruction is to be issued later (Table 8–17). This puts the active configuration controllers into the idle state. The active configuration controller is re-engaged after user mode is reached through JTAG programming (Table 8–17).

While executing the CONFIG_IO instruction, all user I/Os are tri-stated.

If reconfiguration after interruption is performed using configuration modes (rather than using JTAG_PROGRAM), it is not necessary to issue the ACTIVE_DISENGAGE instruction prior to CONFIG_IO. You can start reconfiguration by either pulling nCONFIG low for at least 500 ns or issuing the PULSE_NCONFIG instruction. If the ACTIVE_DISENGAGE instruction was issued and the JTAG_PROGRAM instruction fails to enter user mode, you must issue the ACTIVE_ENGAGE instruction to reactivate the active configuration controller. Issuing the ACTIVE_ENGAGE instruction also triggers reconfiguration in configuration modes; therefore, it is not necessary to pull nCONFIG low or issue the PULSE_NCONFIG instruction.

Device Configuration Pins

Table 8–18 through Table 8–21 describe the connections and functionality of all the configuration related pins on Cyclone IV devices. Table 8–18 and Table 8–19 list the device pin configuration for the Cyclone IV GX and Cyclone IV E, respectively.

Table 8–18. Configuration Pin Summary for Cyclone IV GX Devices

Bank	Description	Input/Output	Dedicated	Powered By	Configuration Mode
8	Data[4:2]	Input	—	V_{CCIO}	FPP
3	Data[7:5]	Input	—	V_{CCIO}	FPP
9	nCSO (2)	Output	—	V_{CCIO}	AS
3	CRC_ERROR	Output	—	V_{CCIO}/Pull-up (1)	Optional, all modes
9	DATA[0] (2)	Input	Yes	V_{CCIO}	PS, FPP, AS
9	DATA[1]/ASDO (2)	Input	—	V_{CCIO}	FPP
		Output		V_{CCIO}	AS
3	INIT_DONE	Output	—	Pull-up	Optional, all modes
3	nSTATUS	Bidirectional	Yes	Pull-up	All modes
9	nCE	Input	Yes	V_{CCIO}	All modes
9	DCLK (2)	Input	Yes	V_{CCIO}	PS, FPP
		Output		V_{CCIO}	AS
3	CONF_DONE	Bidirectional	Yes	Pull-up	All modes
9	TDI	Input	Yes	V_{CCIO}	JTAG
9	TMS	Input	Yes	V_{CCIO}	JTAG
9	TCK	Input	Yes	V_{CCIO}	JTAG
9	nCONFIG	Input	Yes	V_{CCIO}	All modes
8	CLKUSR	Input	—	V_{CCIO}	Optional
3	nCEO	Output	—	V_{CCIO}	Optional, all modes
3	MSEL	Input	Yes	V_{CCINT}	All modes
9	TDO	Output	Yes	V_{CCIO}	JTAG
6	DEV_OE	Input	—	V_{CCIO}	Optional
6	DEV_CLRn	Input	—	V_{CCIO}	Optional

Notes to Table 8–18:

(1) The CRC_ERROR pin is a dedicated open-drain output or an optional user I/O pin. Active high signal indicates that the error detection circuit has detected errors in the configuration SRAM bits. This pin is optional and is used when the CRC error detection circuit is enabled in the Quartus II software from the **Error Detection CRC** tab of the **Device and Pin Options** dialog box. When using this pin, connect it to an external 10-kΩ pull-up resistor to an acceptable voltage that satisfies the input voltage of the receiving device.

(2) To tri-state AS configuration pins in the AS configuration scheme, turn on the **Enable input tri-state on active configuration pins in user mode** option from the **Device and Pin Options** dialog box. This tri-states DCLK, nCSO, Data[0], and Data[1]/ASDO pins. Dual-purpose pins settings for these pins are ignored. To set these pins to different settings, turn off the **Enable input tri-state on active configuration pins in user mode** option and set the desired setting from the Dual-purpose Pins Setting menu.

Table 8–19. Configuration Pin Summary for Cyclone IV E Devices (Part 1 of 3)

Bank	Description	Input/Output	Dedicated	Powered By	Configuration Mode
1	nCSO (1) FLASH_nCE (2)	Output	—	V_{CCIO}	AS, AP
6	CRC_ERROR (3)	Output	—	V_{CCIO}/Pull-up (4)	Optional, all modes

Configuration error detection determines if the configuration data received through an external memory device is corrupted during configuration. To validate the configuration data, the Quartus® II software uses a function to calculate the CRC value for each configuration data frame and stores the frame-based CRC value in the configuration data as part of the configuration bit stream.

During configuration, Cyclone IV devices use the same methodology to calculate the CRC value based on the frame of data that is received and compares it against the frame CRC value in the data stream. Configuration continues until either the device detects an error or all the values are calculated.

In addition to the frame-based CRC value, the Quartus II software generates a 32-bit CRC value for the whole configuration bit stream. This 32-bit CRC value is stored in the 32-bit storage register at the end of the configuration and is used for user mode error detection that is discussed in "User Mode Error Detection".

User Mode Error Detection

☞ User mode error detection is available in Cyclone IV GX and Cyclone IV E devices with 1.2-V core voltage. Cyclone IV E devices with 1.0-V core voltage do not support user mode error detection.

Soft errors are changes in a configuration random-access memory (CRAM) bit state due to an ionizing particle. Cyclone IV devices have built-in error detection circuitry to detect data corruption by soft errors in the CRAM cells.

This error detection capability continuously computes the CRC of the configured CRAM bits based on the contents of the device and compares it with the pre-calculated CRC value obtained at the end of the configuration. If the CRCs match, there is no error in the current configuration CRAM bits. The process of error detection continues until the device is reset (by setting `nCONFIG` to low).

The Cyclone IV device error detection feature does not check memory blocks and I/O buffers. These device memory blocks support parity bits that are used to check the contents of memory blocks for any error. The I/O buffers are not verified during error detection because the configuration data uses flip-flops as storage elements that are more resistant to soft errors. Similar flip-flops are used to store the pre-calculated CRC and other error detection circuitry option bits.

The error detection circuitry in Cyclone IV devices uses a 32-bit CRC IEEE 802 standard and a 32-bit polynomial as the CRC generator. Therefore, a single 32-bit CRC calculation is performed by the device. If a soft error does not occur, the resulting 32-bit signature value is `0x00000000`, that results in a `0` on the `CRC_ERROR` output signal. If a soft error occurs in the device, the resulting signature value is non-zero and the `CRC_ERROR` output signal is `1`.

You can inject a soft error by changing the 32-bit CRC storage register in the CRC circuitry. After verifying the induced failure, you can restore the 32-bit CRC value to the correct CRC value with the same instruction and inserting the correct value.

☞ Before updating it with a known bad value, Altera recommends reading out the correct value.

Table 9–4 defines the registers shown in Figure 9–1.

Table 9–4. Error Detection Registers

Register	Function
32-bit signature register	This register contains the CRC signature. The signature register contains the result of the user mode calculated CRC value compared against the pre-calculated CRC value. If no errors are detected, the signature register is all zeros. A non-zero signature register indicates an error in the configuration CRAM contents. The CRC_ERROR signal is derived from the contents of this register.
32-bit storage register	This register is loaded with the 32-bit pre-computed CRC signature at the end of the configuration stage. The signature is then loaded into the 32-bit CRC circuit (called the Compute and Compare CRC block, as shown in Figure 9–1) during user mode to calculate the CRC error. This register forms a 32-bit scan chain during execution of the CHANGE_EDREG JTAG instruction. The CHANGE_EDREG JTAG instruction can change the content of the storage register. Therefore, the functionality of the error detection CRC circuitry is checked in-system by executing the instruction to inject an error during the operation. The operation of the device is not halted when issuing the CHANGE_EDREG instruction.

Error Detection Timing

When the error detection CRC feature is enabled through the Quartus II software, the device automatically activates the CRC process upon entering user mode after configuration and initialization is complete.

The CRC_ERROR pin is driven low until the error detection circuitry detects a corrupted bit in the previous CRC calculation. After the pin goes high, it remains high during the next CRC calculation. This pin does not log the previous CRC calculation. If the new CRC calculation does not contain any corrupted bits, the CRC_ERROR pin is driven low. The error detection runs until the device is reset.

The error detection circuitry runs off an internal configuration oscillator with a divisor that sets the maximum frequency.

Table 9–5 lists the minimum and maximum error detection frequencies.

Table 9–5. Minimum and Maximum Error Detection Frequencies for Cyclone IV Devices

Error Detection Frequency	Maximum Error Detection Frequency	Minimum Error Detection Frequency	Valid Divisors (2^n)
80 MHz/2^n	80 MHz	312.5 kHz	0, 1, 2, 3, 4, 5, 6, 7, 8

You can set a lower clock frequency by specifying a division factor in the Quartus II software (for more information, refer to "Software Support"). The divisor is a power of two (2), where *n* is between 0 and 8. The divisor ranges from one through 256. Refer to Equation 9–1.

Equation 9–1.

$$\text{error detection frequency} = \frac{80\ \text{MH}}{2^n}$$

CRC calculation time depends on the device and the error detection clock frequency.

In some applications, it is necessary for a device to wake up very quickly to begin operation. Cyclone IV devices offer the Fast-On feature to support fast wake-up time applications. The MSEL pin settings determine the POR time (t_{POR}) of the device.

For more information about the MSEL pin settings, refer to the *Configuration and Remote System Upgrades in Cyclone IV Devices* chapter.

For more information about the POR specifications, refer to the *Cyclone IV Device Datasheet* chapter.

Document Revision History

Table 11–3 lists the revision history for this chapter.

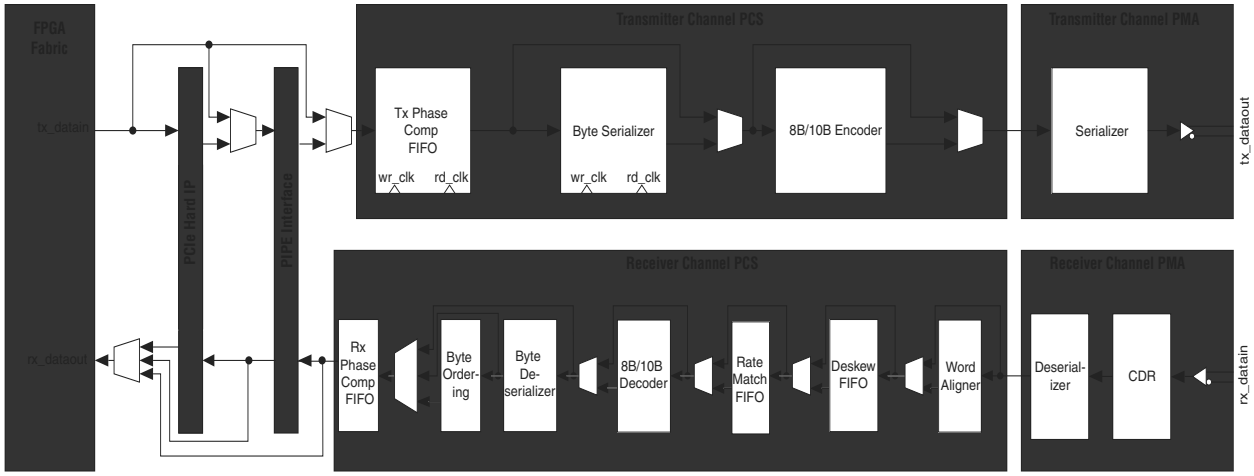
Table 11–3. Document Revision History

Date	Version	Changes
May 2013	1.3	Updated Note (4) in Table 11–1.
July 2010	1.2	■ Updated for the Quartus II software version 10.0 release. ■ Updated "I/O Pins Remain Tri-stated During Power-Up" section. ■ Updated Table 11–1.
February 2010	1.1	Updated Table 11–1 and Table 11–2 for the Quartus II software version 9.1 SP1 release.
November 2009	1.0	Initial release.

Architectural Overview

Figure 1–3 shows the Cyclone IV GX transceiver channel datapath.

Figure 1–3. Transceiver Channel Datapath for Cyclone IV GX Devices



Each transceiver channel consists of a transmitter and a receiver datapath. Each datapath is further structured into the following:

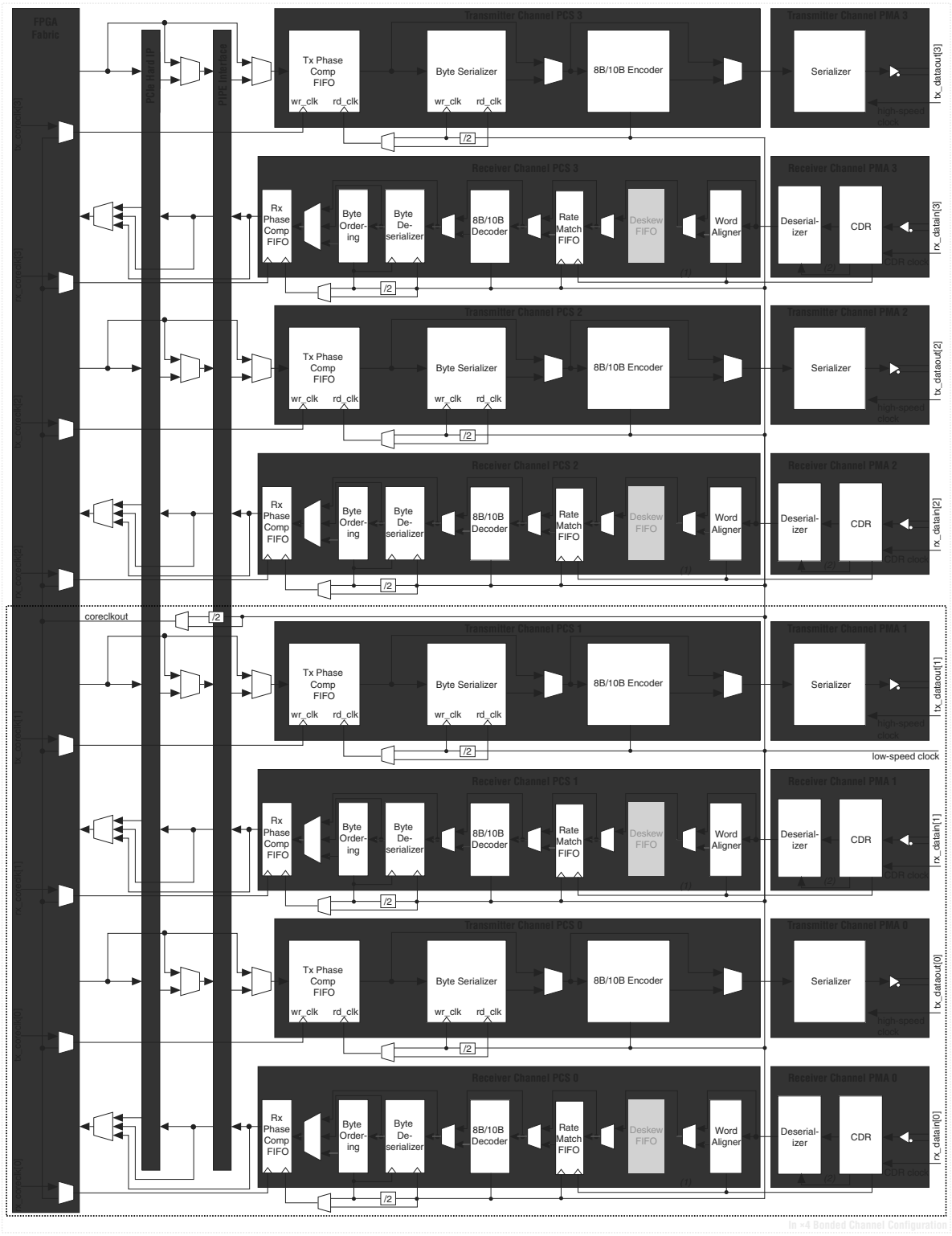
- Physical media attachment (PMA)—includes analog circuitry for I/O buffers, clock data recovery (CDR), serializer/deserializer (SERDES), and programmable pre-emphasis and equalization to optimize serial data channel performance.
- Physical coding sublayer (PCS)—includes hard logic implementation of digital functionality within the transceiver that is compliant with supported protocols.

Outbound parallel data from the FPGA fabric flows through the transmitter PCS and PMA, is transmitted as serial data. Received inbound serial data flows through the receiver PMA and PCS into the FPGA fabric. The transceiver supports the following interface widths:

- FPGA fabric-transceiver PCS—8, 10, 16, or 20 bits
- PMA-PCS—8 or 10 bits

The transceiver channel interfaces through the PIPE when configured for PCIe protocol implementation. The PIPE is compliant with version 2.00 of the *PHY Interface for the PCI Express Architecture* specification.

Figure 1–39. Transmitter and Receiver Datapath Clocking with Rate Match FIFO in Bonded Channel Configuration



Notes to Figure 1–39:

(1) Low-speed recovered clock.

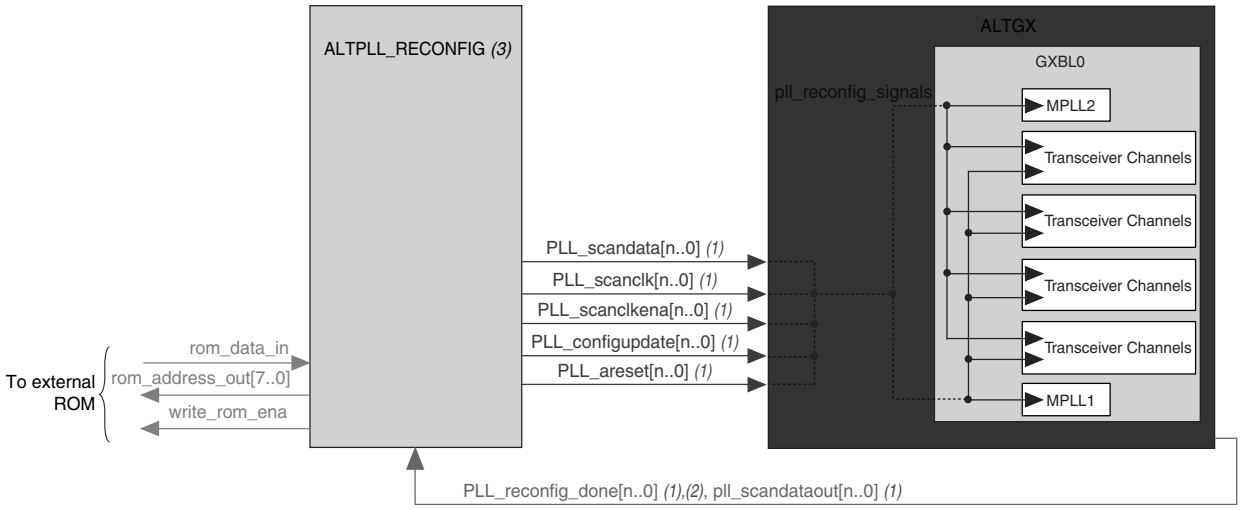
(2) High-speed recovered clock.

The .**mif** files carries the reconfiguration information that will be used to reconfigure the multipurpose PLL or general purpose PLL dynamically. The .**mif** contents is generated automatically when you select the **Enable PLL Reconfiguration** option in the **Reconfiguration Setting** in ALTGX instances. The **.mif** files will be generated based on the data rate and input reference clock setting in the ALTGX MegaWizard. You must use the external ROM and feed its content to the ALTPLL_RECONFIG megafunction to reconfigure the multipurpose PLL setting.

For more information about instantiating the ALTPLL_Reconfig, refer to the *AN 609: Implementing Dynamic Reconfiguration in Cyclone IV GX Devices*.

Figure 3–16 shows the connection for PLL reconfiguration mode.

Figure 3–16. ALTGX and ALTPLL_RECONFIG Connection for PLL Reconfiguration Mode



Notes to Figure 3–16:

(1) *<n>* = (number of transceiver PLLs configured in the ALTGX MegaWizard) - 1.

(2) You must connect the `pll_reconfig_done` signal from the ALTGX to the `pll_scandone` port from ALTPLL_RECONFIG.

(3) You need two ALTPLL_RECONFIG controllers if you have two separate ALTGX instances with transceiver PLL instantiated in each ALTGX instance.

For more information about connecting the ALTPLL_RECONFIG and ALTGX instances, refer to the *AN 609: Implementing Dynamic Reconfiguration in Cyclone IV GX Devices*.

Table 1–25. PLL Specifications for Cyclone IV Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Min	Typ	Max	Unit
t_{DLOCK}	Time required to lock dynamically (after switchover, reconfiguring any non-post-scale counters/delays or areset is deasserted)	—	—	1	ms
$t_{OUTJITTER\_PERIOD\_DEDCLK}$ (6)	Dedicated clock output period jitter $F_{OUT} \geq 100$ MHz	—	—	300	ps
	$F_{OUT} < 100$ MHz	—	—	30	mUI
$t_{OUTJITTER\_CCJ\_DEDCLK}$ (6)	Dedicated clock output cycle-to-cycle jitter $F_{OUT} \geq 100$ MHz	—	—	300	ps
	$F_{OUT} < 100$ MHz	—	—	30	mUI
$t_{OUTJITTER\_PERIOD\_IO}$ (6)	Regular I/O period jitter $F_{OUT} \geq 100$ MHz	—	—	650	ps
	$F_{OUT} < 100$ MHz	—	—	75	mUI
$t_{OUTJITTER\_CCJ\_IO}$ (6)	Regular I/O cycle-to-cycle jitter $F_{OUT} \geq 100$ MHz	—	—	650	ps
	$F_{OUT} < 100$ MHz	—	—	75	mUI
t_{PLL_PSERR}	Accuracy of PLL phase shift	—	—	±50	ps
t_{ARESET}	Minimum pulse width on areset signal.	10	—	—	ns
$t_{CONFIGPLL}$	Time required to reconfigure scan chains for PLLs	—	3.5 (7)	—	SCANCLK cycles
$f_{SCANCLK}$	scanclk frequency	—	—	100	MHz
$t_{CASC\_OUTJITTER\_PERIOD\_DEDCLK}$ (8), (9)	Period jitter for dedicated clock output in cascaded PLLs ($F_{OUT} \geq 100$ MHz)	—	—	425	ps
	Period jitter for dedicated clock output in cascaded PLLs ($F_{OUT} < 100$ MHz)	—	—	42.5	mUI

Notes to Table 1–25:

(1) This table is applicable for general purpose PLLs and multipurpose PLLs.

(2) You must connect V_{CCD_PLL} to V_{CCINT} through the decoupling capacitor and ferrite bead.

(3) This parameter is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

(4) The V_{CO} frequency reported by the Quartus II software in the PLL Summary section of the compilation report takes into consideration the V_{CO} post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.

(5) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source that is less than 200 ps.

(6) Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.99999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL when an input jitter of 30 ps is applied.

(7) With 100-MHz scanclk frequency.

(8) The cascaded PLLs specification is applicable only with the following conditions:

- Upstream PLL—0.59 MHz ≤ Upstream PLL bandwidth < 1 MHz
- Downstream PLL—Downstream PLL bandwidth > 2 MHz

(9) PLL cascading is not supported for transceiver applications.